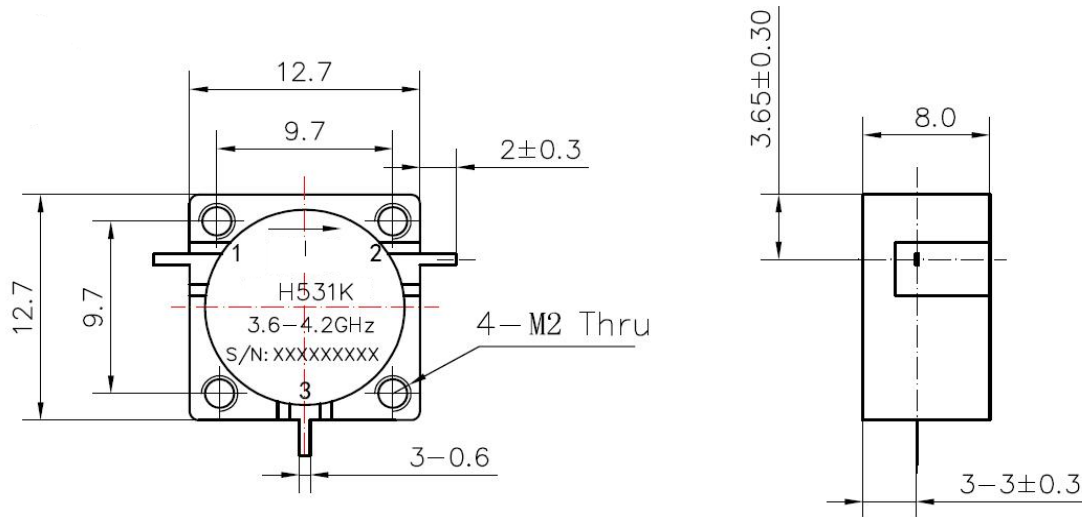


1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H531K[3.6-4.2]GHz	3.600	4.200	3.9000	0.600	20	0.35	1.25	50	
H531K[3.7-4.13]GHz	3.700	4.130	3.9150	0.430	20	0.35	1.25	50	
H531K[4.4-5]GHz	4.400	5.000	4.7000	0.600	20	0.35	1.25	50	
H531K[5.15-5.9]GHz	5.150	5.900	5.5250	0.750	20	0.35	1.25	50	
H531K[7.1-7.5]GHz	7.100	7.500	7.300	0.400	22	0.4	1.2	10	
H531K[9.2-9.8]GHz	9.200	9.800	9.500	0.600	21	0.4	1.2	60	
H531K[10.1-10.6]GHz	10.100	10.600	10.350	0.500	22	0.4	1.2	20	